

PRODUCT TYPE	Quartz Crystal HSX530G					
NOMINAL FREQUENCY	8.00000MHz					
H.ELE. SAMPLE O/N	EOS-IB0115-9					
H.ELE. P/N	X5H008000IK1H-H					
RELEASE DATE	2018/11/09					
VERSION	00					
MSL	Level 1					
<b>GREEN PRODUCT</b>	Pb free  RoHS Compliant					
	🗹 HF-Halogen free 🗹 REACH Compliant					
CUSTOMER P/N						
<b>APPLICATION &amp; MODEL</b>						
APPROVED BY CUSTOME	ER					
	(DATE)					
Harmony Electronics Corp.						

<u>C. C. HOU</u> (CHECK)	U. F. CHEN (PREPARE)	Country of Origin: Taiwan Factory Thailand Factory China Factory
HARM	IONY ELECTRO	ONICS CORPRATION

THAILAND

SHENZHEN

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KAOHSIUNG

TEL: 886-2-26588883



REV. No.	DATE	REASON	REVISE CONTENTS
0	2018/11/09	New	

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## **1. QUARTZ CRYSTAL UNIT SPECIFICATION**

	Ele	ctrical Spe	с.		
Items	Items Unit Min Type Max		Notes		
1. Frequency (FL)		8.000000		MHz	
2. Mode of oscillation:	F	undament	al		
3. Frequency tolerance	-50		+50	ppm	at 25°C±3°C
4. Equivalent resistance (RR)			100	Ω	SERIES
5. Storage temperature range	-40		+85	°C	
6. Operable temperature range	-20		+70	°C	
7. Temperature stability	-50		+50	ppm	-20°C ~ +70°C
8. Loading capacitance (CL)		20.0		рF	
9. Drive level (DL)		10	300	μW	
10. Shunt Capacitance (C0)			7.0	pF	
11. Insulation resistance	500			MΩ	at DC 100V
12. Aging:	-5		+5	ppm/Year	
13. Circuit:	Measured	l in HP/E51	00A,S&A 2	250B	

Note: Storage Temperature is only for the product itself.

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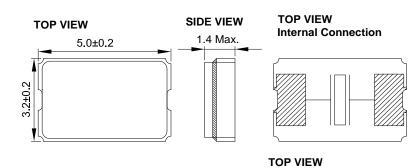
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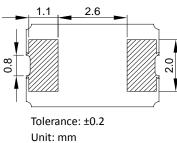
Shenzhen

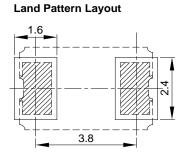
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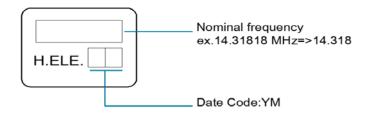






\* Note: The Index mark was defined by the BASE suppliers.

### 3. MARKING



Note:

1. Laser marking.

2. Date Code:

V. Veer	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019
Y=Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	0	1	2	3	4	5	6	7	8	9

M=Month	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Code	А	В	С	D	E	F	G	Н	J	К	Ľ	М

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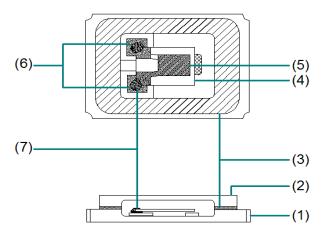
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### 4. INSIDE STRUCTURE



No.	Component	Material	Note
(1)	Base- Ceramic	Ceramic	Al <sub>2</sub> O <sub>3</sub>
(2)	Cap-Ceramic	Ceramic	Al <sub>2</sub> O <sub>3</sub>
(3)	Crystal-Seal	Glass	-
(4)	Crystal Blank	Quartz	SiO₂ Rectangular At-Cut
(5)	Electrode	Metal	-
(6)	PAD	Metal	W Ni Plating Au Plating
(7)	Connective Adhesive	Silver Powder	Ag

Poforonco drawing

**X**The use prohibition chemistry substance of Table 1 of DHE-0204-1 (HE-QA-24) is not included in this item.

### **5. HANDLING SUGGESTION**

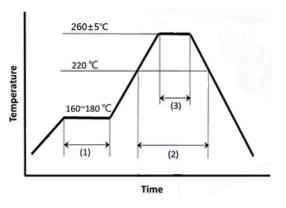
#### Reflow Condition

Please stay with our proposed reflow condition and do soldering within 2 times.

(1)	Preheat	160~18	0deg.C	120 sec.
(2)	Primary heat	>=220	deg.C	100±20 sec.
(3)	Peak	260±5	deg.C	10 sec. Max.

### Manual Solder iron (Example)

Bit temp.:  $350^{\circ}$ C max., Time: 3sec max., Each terminal only should be soldered once.



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#### Mounting Conditions

Our products are suitable for most automated SMT processes. However, we strongly advise all our customers to conduct SMT sampling prior to mass production in order to make sure production processes will not affect the properties and specifications of our product. Seal welding and mounting procedures involving the use of ultra-sonic processes are not recommended and will affect and/or damage the internal properties of our product. Excessive shock during the mounting process will also affect the product and we strongly recommend setting SMT conditions to minimize such conditions.

If a possibility of the PCB being warped exists we strongly advise to ensure the degree of warping will not affect the product.

Please also ensure the operating characteristics and or soldering conditions are all within the specifications of use for our product.

Ultimately the worst case scenario of all the above will lead to cases of non-oscillation but other negative effects are also likely should our products be used in an inappropriate way. Please note such cases of misuse and its related quality issues are not included in our product warranty.

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#### Cleansing Conditions

General cleaning solutions may be used to clean our products but we always recommend testing to be performed prior to mass production processes. Ultrasonic cleaning procedures are not recommended and we strongly advise other forms of cleansing to be evaluated first. Unsuitable cleansing may lead to a number of negative effects such as damage to the product surface, discoloration of the product, corrosion of the package, package contamination, illegible marking, etc. Please note cases of unadvised treatment and its related quality issues are not included in our product warranty.

#### Storage Conditions

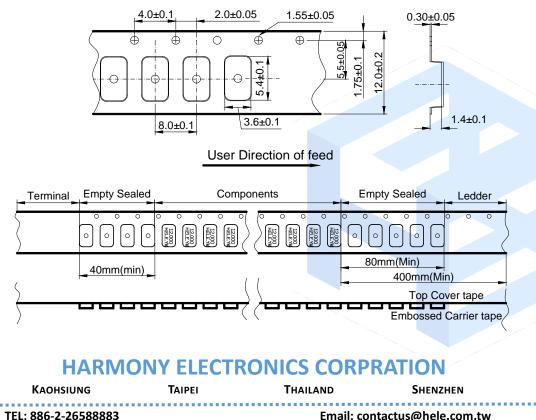
Please ensure our products are preserved appropriately in their original packaging. Irregular environmental instances of moisture will affect our product's stability and may cause problems such as frequency instability, soldering ability and conditions, package defects, and other problems. It is essential to keep our products in a clean dust-free environment out of direct sunlight.

Our products' storage conditions should at least meet the following condition: Environmental Temperature: + 40 degrees Celsius Maximum Relative Humidity: 80% Maximum

Please note storage instances which do not conform to our guidelines and the related quality issues produced as an outcome are not included in our product warranty.

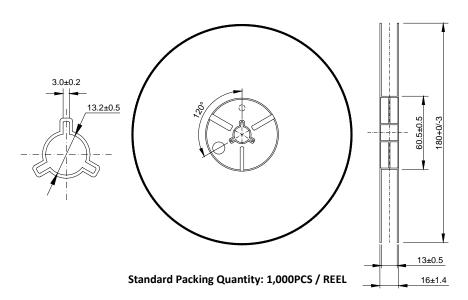
#### 6. EMBOSS CARRIER TAPE AND REEL

#### Carrier Tape





Reel



#### Material of The Tape

Таре	Material
Carrier tape	PS Conductive
Top tape	PET

#### Joint of tape

The carrier-tape and top cover-tape should not be jointed.

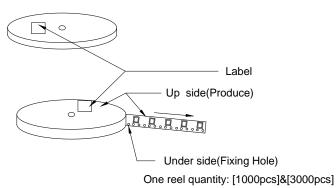
### Release strength of cover tape

The force should be controlled between 0.1N to 0.7N under following condition. Pulling direction: 165° to 180° Speed: 300mm/min. Otherwise unless specified.



Other standards shall be based on JIS C 0806-1990.

### 7. PACKAGE





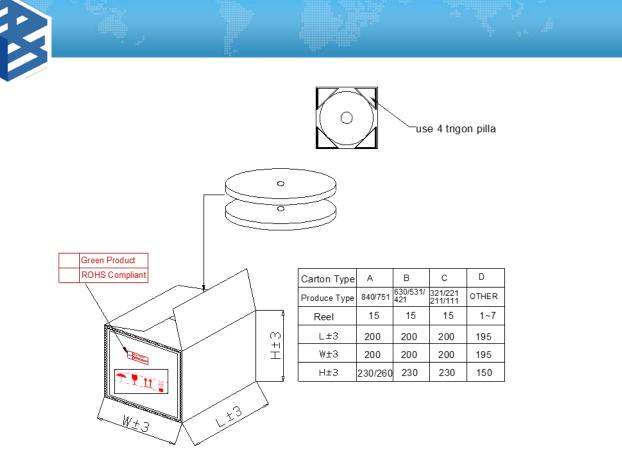
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(1)Top and bottom with 2.3cm thickness

- foam-rubber cushion for protection.
- ②Carton's Q'TY:1~15 pcs.
- ③Carton Type=A,B,C use 4 trigon pillar to fasten the Reel.
- (4)Need to add 3 pages dry agent in each outer box.

#### 8. MECHANICAL PERFORMANCE

	Item Test Methods					
1	Shock	Dropping from 100 cm height 3 tim Refer to: JIS C 60068-2-32	А			
2	Vibration	Frequency 10-55Hz, Sine Wave full 3 axes, 2 cycles and duration of 2 h Refer to: JIS C 60068-2-6/ MIL-HDB	Α			
3	Leakage Test	Leak Rate 1.0x10 <sup>-9</sup> Pa-m <sup>3</sup> /sec. Max. detector. Refer to: JIS C 60068-				
4	Solder ability	After applying ROSIN Flux, dipping for 3 ±0.5 sec. Refer to: JIS C 60068-2-20/ JIS C 60	В			
5	Bending Strength	Mount a sample on board. Apply Pressure to the center of board until it is bent to 3 mm and hold for 5 ±1 sec. Pressure speed: 0.5 mm/sec. Refer to: EIAJ ET-7403/ JIS C 60068-2-21	Pressure rod 20 $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{230}$ $\mathbb{R}^{23$	A		

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6	Adhesion	Mount a sample on the circuit board. Apply pressure vertically to the side of specimen attached to the circuit board with the pressure jig. Pressure: 5N for 10±1 sec. Refer to: EIAJ ET-7403 JIS C 60068-2-21	Scratch tool	С
7	Body strength	Apply pressure to the center of body with the R0.5 pressure jig. pressure :10N for 10±1sec Refer to: EIAJ ET-7403 JIS C 60068-2-21	$\begin{array}{c c} & \text{Pressure rad} \\ \hline \\ Pressure \\ \hline \\ R0.5 \\ \hline \\ Chip \\ \hline \\ U \\ L \\ L \\ W \\ \hline \\ L \\ \hline \\ W \\ \hline \end{array}$	с

### 9. ENVIRONMENT PERFORMANCE

	Item Test Methods		Specifications Code
1	Resistance of Soldering Heat	Performing as the following reflow: Refer to: JIS C 60068-2-58	A
2	Humidity	Temperature 60°C±2°C, RH 90~95%, duration of 240 hours. Back to room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-3	А
3	Storage in Low Temperature	-40deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-1	A
4	Storage in High Temperature	+85deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-2	A
5	Thermal shock	-55deg.C ±2deg.C (30min) ↔ +125deg.C ±2deg.C (30min) 25 cycles. And Temperature Increasing/reducing time ≦ 3mins. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 0025	A

Specifications code	Specifications		
Α	FREQ. DRIFT: $\pm 5$ ppm Max, RESISTANCE DRIFT: $\pm 15\%$ or $2\Omega$		
В	More than 90% of lead shall be covered by new solder.		
C	FREQ. DRIFT: ±15 ppm Max, RESISTANCE DRIFT: ±25% or $10\Omega$		

## HARMONY ELECTRONICS CORPRATION

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#### **FACTORY LOCATION**

#### HEAD OFFICE/TAIWAN FACTORY

NO.39, HUADONG RD., DALIAO DIST., DAFA INDUSTRIAL PARK, KAOHSIUNG CITY 831, TAIWAN.

#### **CHINA FACTORY**

JU YUAN INDUSTRIAL PARK, QIAO TANG ROAD, TANG WEI COMMUNITY, FUYONG, BAOAN DISTRICT, SHEN ZHEN CITY, CHINA (Post Code:518103).

#### **THAILAND FACTORY**

66MOO 5, KAONGU-BEOKPRAI RD., T.BEOKPRAI, A. BANPONG, RATCHABURI PROVINCE 70110, THAILAND.

#### **SERVICE CENTER**

#### **TAIPEI OFFICE**

2F., NO.409, SEC.2, TIDING BLVD., NEIHU DISTRICT, TAIPEI CITY 114, TAIWAN TEL: 886-2-26588883 FAX: 886-2-26588683

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